

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2513548	spring or bolster adj plate or curved adj plate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:28
L2	26688	chip adj package or semiconductor adj die	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:28
L3	2703	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:28
L4	1214954	model or calculate or (computer adj aided adj design or CAD)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:29
L5	583	3 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:47
L6	1657	((438/117) or (438/121) or (438/122)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/31 08:30
L7	1	5 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:30
L8	33	spring adj design and finite adj element	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:49

L10	56	FEA adj software	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:58
L11	4272	(FEA adj software) or (finite near element near analysis)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:59
L12	1602	11 and plate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 09:01
L13	1	6 and 12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 09:01
L14	2	("6095008" "6120006").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/31 09:02
L15	314347	(arc or bend or bent or bow or bowed or bowing or curvature or arch or arched or camber or cambered or turned or curve or curved or curving) near4 (plate or sheet or flatter or reinforce or re-inforce or reinforced or re-inforced or reinforcing or re-inforcing or support or supporting or supported or strengthen)	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/31 09:06
L16	338	15 and 11	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/31 09:06

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